

DISCRIPTION

FEATURES

Multilayer ceramic structure
 Closed magnetic circuit
 Avoids crosstalk
 Excellent solderability
 High reliability

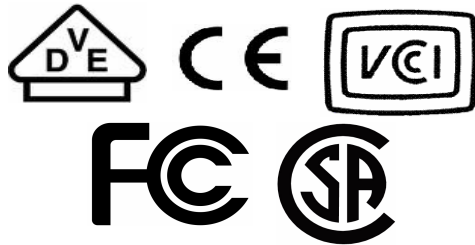
OPTIONS

Tape & Reel is Standard (Qty: 2.000 Pcs)
 Bulk Packing Available for smaller quantities
 Tolerance: K=10%, M=20% is Standard,
 tighter Tolerance available (MOQ on request)

APPLICATIONS

VCRs
 Mobile Radios
 Cordless Telephones
 Modems
 Global Position Systems
 Wirless Communications Equipment
 Network Systems
 Computer Products

APPROVAL



PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Inductance & Q-HP4195A + HP41951
 DCR : VOAC-7412 ; SRF : HP8753C
- Solderability : 75% of the terminal Electrode shall be covered
 Preheat : 180°C ± 5°C for 2 ~ 3 minutes
 Solder temperature : 230°C for 4 seconds ± 1 second
 Flux : Emersion into methanol solution with Colophony for 3 to 5 seconds.
- IDC : The DC current at which tither the initial L value is decreased
 by 5% with the application of DC bias or the value of current at which
 the tempature of the element is increased by 20°C
- Operating Temperature : -40°C ~ 100°C

ELECTRICAL SPECIFICATIONS

| Properties | Test conditions | | Value | Unit | Tol. |
|--------------------|-----------------|-----------------|-------|------|------------|
| Inductance | | L | 15 | µH | see Site 2 |
| Q factor | | Q | 20 | | min. |
| DC-resistance | | DCR typ. | --- | Ω | typ. |
| DC-resistance | | DCR max. | 1,7 | Ω | max. |
| Self-Res. Freq. | | SRF | 14 | Mhz | min. |
| Test-Freq. | | | 1 | Mhz | |
| Rated Current | | IDC | 1 | mA | max. |
| Saturation Current | | Isat | --- | mA | typ. |

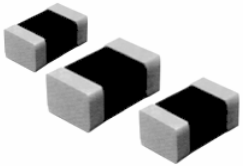
1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon -Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability functions.

SMT Multi-Layer Ceramic Chip Inductors

Part No.: **S11005-150**

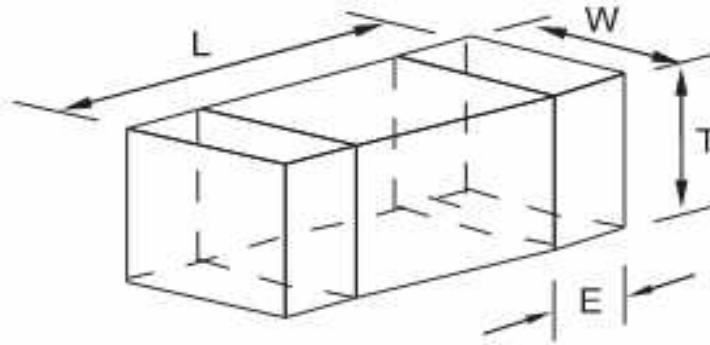
Customer:

| | | | | | | | |
|-------|-------|------|-------|--------|---------|-------|------------|
| DRW: | Chang | CHKD | Young | MATL: | Chu Chi | DATE | 08.06.2009 |
| APPD: | Pong | | | FINISH | Vienna | Sheet | 1 from 2 |



TECHNICAL INFORMATIONS

Dimensions (mm)



| L |
|------------|
| 1,6 ± 0,15 |

| W |
|------------|
| 0,8 ± 0,15 |

| T |
|------------|
| 0,8 ± 0,15 |

| E |
|------------|
| 0,3 ± 0,20 |

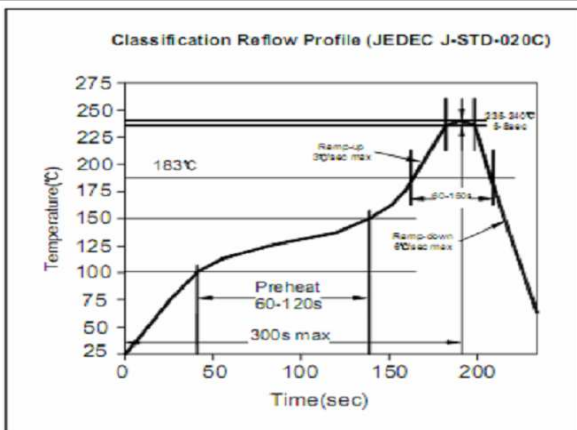
Ordering Information

| Serie and Range |
|-----------------|
| S11005-150 |

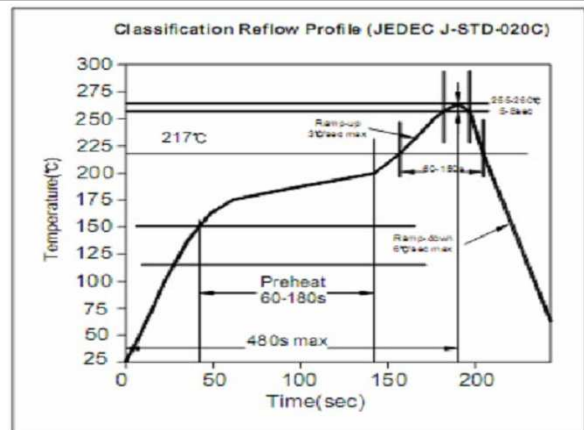
| Tolerance | ROHS | Packing |
|-----------|------|---------|
| K | R | TR |

| | | |
|---------|--------------|----------------|
| K = 10% | R = ROHS | BU = Bulk Ware |
| M = 20% | N = non ROHS | TR = Tape Reel |
| N = 30% | | |

**Soldering Profile for Lead Free Soldering
 235-240°C**



**Soldering Profile for Lead Free Soldering
 255-260°C**



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 Ceramic Chip Inductors**

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